



RE900

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for 14 different SMD TSOP I and 7 different SMD TSOP II chips
- Pitch 0.40 mm (15.7 mil); 0.50 mm (19.7 mil); 0.65 mm (26.5 mil); 0.80 mm (30 mil); 1.27 mm (50 mil)
- Hole diameter 1.00 mm
- Prescratched rated break point for the separation of individual moduls from the board
- Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
- Size: 72.60 x 76.20 mm

Modul-No.	Type	Pitch	Pin	Size (mm)
RE900-01	TSOP I	0.400 mm	28, 40, 48, 60	12.00 x 18.00
RE900-02	TSOP I	0.500 mm	28, 32, 40, 48	12.00 x 20.00
RE900-03	TSOP I	0.500 mm	20, 24	6.00 x 16.00
RE900-04	TSOP I	0.650 mm	16, 24, 28, 36	12.00 x 14.00
RE900-05	TSOP II	0.800 mm	40, 44	11.50 x 18.80
RE900-06	TSOP II	1.270 mm	20, 24, 26, 28, 32	11.50 x 21.30